

L Number	Hits	Search Text	DB	Time stamp
1	68925	(bump ball) and (polymer polymeric polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 15:05
2	1605	(bump ball) and (polymer polymeric polyimide) and (metal adj coat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 15:45
3	0	("JP405335316a").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 15:15
4	0	("JP405335316").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 15:15
5	6	("3880486"   "3986255"   "4125310"   "4403272"   "4548451"   "4581679").PN.	USPAT	2003/10/14 15:41
6	2191	257/736-738,778-779.ccls. and (bump ball) and substrate and (die chip IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 15:58
7	1	("6365500").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 15:50
8	11	("3401126"   "3763550"   "3809625"   "4749120"   "4865245"   "4916523"   "4963002"   "4965227"   "5134460"   "5298331"   "5331235").PN.	USPAT	2003/10/14 15:50
9	2097	257/737-738.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 16:08
10	1746	257/778.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/14 16:09